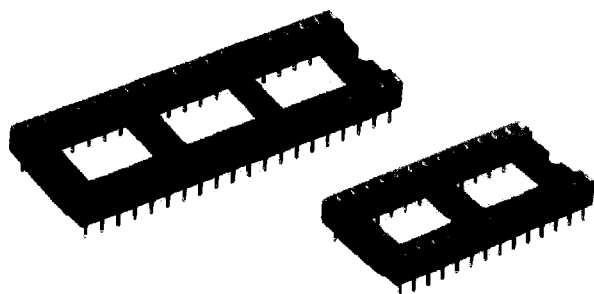


IC 30 SERIES DIP(2.54mm pitch)



FEATURES

- Dual wipe leaf spring contact ensures outstanding reliability.
- Ideal for high-density mounting at 2.54mm pitch end to end.

SPECIFICATIONS

PERFORMANCE

Insulation Resistance	1,000M Ω min. at 500VDC
Dielectric Withstanding Voltage	700VAC rms for 1 minute
Contact Resistance	20m Ω max. at 10mA
Current Rating	1A
Operating Temperature Range	-65°C to +80°C

MATERIAL AND FINISH

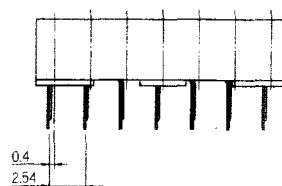
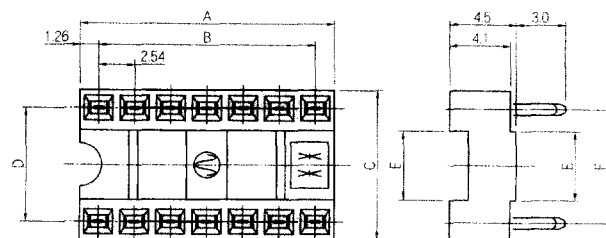
Housing	PBT (glass-filled), UL94V-0 rated
Contacts	Copper alloy, gold or tin plating over nickel

ORDERING CODE

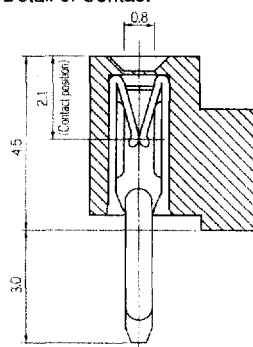
IC30—1403—G4

IC30 series	
	Straight solder dip terminal
	Type of contact plating: G = Gold, S = Tin
	Distance between IC terminal rows: 3 = 0.3 inches
	Number of leads

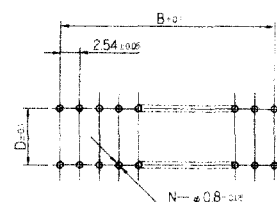
●Outline Dimensions



●Detail of Contact



●Recommended PC Board Patterns (TOP VIEW)



Part No.	No. of Leads	A	B	C	D	E
IC30—0803—*4	8	10.13	2.54×3=7.62	10.13	7.62	4.5
IC30—1003—*4	10	12.67	2.54×4=10.16	10.13	7.62	4.5
IC30—1403—*4	14	17.75	2.54×6=15.24	10.13	7.62	4.5
IC30—1603—*4	16	20.29	2.54×7=17.78	10.13	7.62	4.5
IC30—1803—*4	18	22.83	2.54×8=20.32	10.13	7.62	4.5
IC30—2003—*4	20	25.37	2.54×9=22.86	10.13	7.62	4.5
IC30—2004—*4	20	25.37	2.54×9=22.86	12.67	10.16	6.5
IC30—2203—*4	22	27.91	2.54×10=25.40	10.13	7.62	4.5
IC30—2204—*4	22	27.91	2.54×10=25.40	12.67	10.16	6.5
IC30—2403—*4	24	30.45	2.54×11=27.94	10.13	7.62	4.5
IC30—2406—*4	24	30.45	2.54×11=27.94	17.75	15.24	11.0
IC30—2803—*4	28	35.53	2.54×13=33.02	10.13	7.62	4.5
IC30—2806—*4	28	35.53	2.54×13=33.02	17.75	15.24	11.0
IC30—3206—*4	32	40.61	2.54×15=38.10	17.75	15.24	11.0
IC30—3606—*4	36	45.69	2.54×17=43.18	17.75	15.24	11.0
IC30—4006—*4	40	50.77	2.54×19=48.26	17.75	15.24	11.0
IC30—4206—*4	42	53.31	2.54×20=50.80	17.75	15.24	11.0
IC30—6409—*4	64	81.25	2.54×31=78.74	25.37	22.86	18.0

Unit = mm